

THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD

.050R NOTCH

PIN NO. 1

INDEX MARK

1.000 ±.010

.780 ±.008

.680 ±.008

.600 ±.007

THIS METALLIZED SURFACE TO BE FLAT WITHIN .003 TIR.

20

19

12

11

.020 R TYP.

.032 R TYP.

.050 TYP.

.035 ±.010

45°

.018 ±.002 TYP.

.175

.330

.360 ±.020

TYP. .031 DIA

VENDOR'S OPTION

.100 ±.005

.060

.900 ±.005

TOL NON ACCUM.

.090 ±.010

.025 ±.003

.025 ±.003

±.004

.040

+ .002
- .001

AD
0Y42

(AT STAND OFF)
300 ±.010

CERAMIC
KYOCERA A440
(BLACK)

BRAZED
Ag-Cu ALLOY

CHAMFER
VENDOR'S OPTION



DETAIL - A

VENDOR'S OPTION

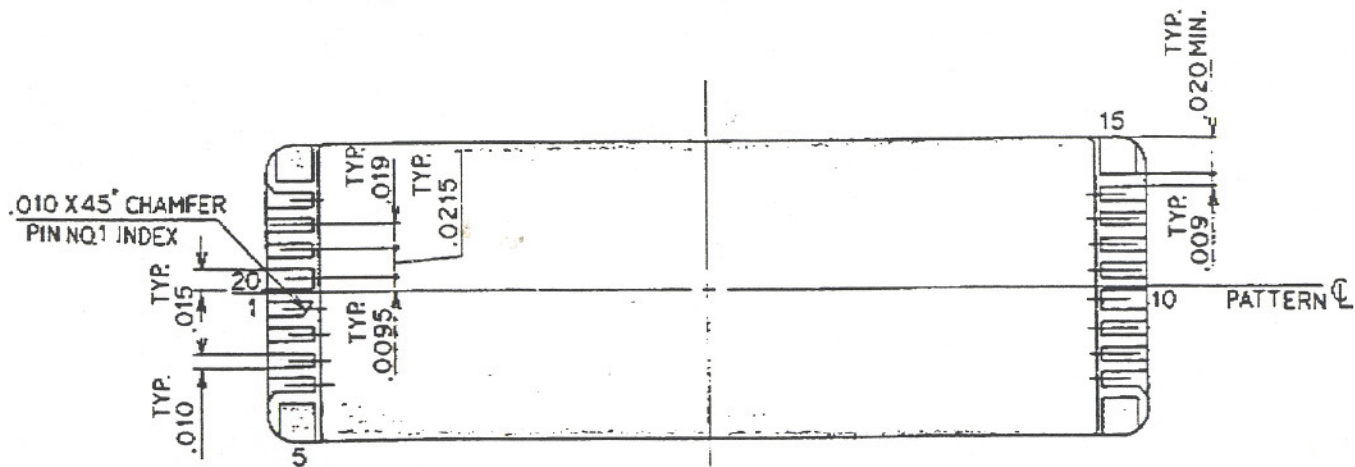
S8020T745-1 S=0
D=0

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME 20 LEAD SIDE BRAZED PACKAGE		TOLERANCES UNLESS OTHERWISE SPECIFIED ±.005
SCALE 5 : 1	MATERIAL AS INDICATED	
KYOCERA CORPORATION		

DRAWN	CHECKED
APPROVED	DATE
	SEP 21 '87
DWG. NO. KD-S87745	1/2

KYOTO JAPAN



BONDING PATTERN

NOTES

- 1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
- 2. SEAL AREA TO BE METALLIZED
- 3. DIE ATTACH AREA TO BE METALLIZED
- 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
- 5. LEAD RESISTANCE: 0.15 Ω MAX. AT PIN NO. 10. 20 OTHER LESS THAN 0.3 Ω MAX.

MODIFICATIONS						NAME 20 LEAD SIDE BRAZED PACKAGE SCALE 10 : 1 MATERIAL TOLERANCES UNLESS OTHERWISE SPECIFIED KYOCERA CORPORATION KYOTO JAPAN	DWG. NO. KD-S87745		
								DRAWN <i>Shimizu</i> CHECKED <i>Shimizu</i> APPROVED <i>Shimizu</i> DATE	DATE SEP. 21 '87
	CHANGE		DATE	DRAWN	CHECKED	APPROVED			